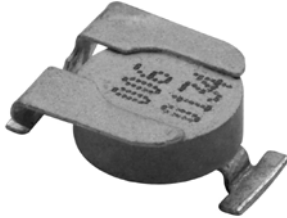




## Horizontal Surface Mount PTC Thermistors For Overload Protection



### FEATURES

- Ideal for pick-and-place circuit assembly
- Low mounting height
- Suitable for reflow soldering
- Small ceramic diameter for faster response
- Low heat transfer to substrate
- Flat terminations for stable positioning and good solderability.

### APPLICATIONS

- Telecom
  - Central office switching (C.O.)
  - Subscriber terminal equipment (T.E.)
  - Set top box
  - Modems
  - Cable TV communications
- General industry and automotive
  - Low power supplies overload protection
  - Data bus protection.

### DESCRIPTION

The component consists of a high-performance PTC ceramic disc mounted in a lead-frame for direct soldering onto a printed-circuit board (PCB) or substrate.

The ceramic is soldered to the leadframe by a local reflow process, during which the solder layer is melted to the metallized ceramic surface using a low residue flux.

### MARKING

- All SMD PTCs are marked with the last 3-digits of the type number (XXX) and a date code (YYWW).

QUICK REFERENCE DATA		
DESCRIPTION	VALUE	
	STANDARD TYPES <sup>(1)(2)</sup>	TELECOM TYPES <sup>(1)(2)</sup>
Nominal R25	2 to 500	10 to 70
Resistance tolerance	±10%; ±15%; ±20%	
Maximum overload current (voltage dependent)	2 to 10 A	
Non-trip current	50 to 500 mA at 25 °C	50 to 100 mA at 70 °C
Maximum voltage	16 to 400 V (RMS)	220 to 600 V (RMS)
Response time at 25 °C and 20 W overload power	<1 s	
Matching	–	down to 0.5 Ω
Maximum continuous power at	2 W	

#### Notes

1. Customized products are available on request.
2. Coated and/or reinforced types are available on request.

ELECTRICAL DATA AND ORDERING INFORMATION									
RESISTANCE		MATCHING Ω	V MAX. (V)	I <sub>nt</sub> at		I <sub>t</sub> at	MAX. TRIP-TIME at 1 A (s)	I <sub>max</sub> at V <sub>max</sub> (A)	CATALOG NUMBER 2322 661 .....
R <sub>25</sub> (Ω)	TOL (%)			25 °C (mA)	70 °C (mA)	25 °C (mA)			
<b>Telecommunication types</b>									
10	20	no	245	165	100	270	3.0	2.0	97012 <sup>(1)</sup>
10	20	0.5	245	165	100	270	3.0	2.0	97016 <sup>(1)</sup>
40	25	no	265	80	50	130	0.8	2.0	97002
25	20	1	265	120	70	220	1.3	2.0	97005 <sup>(1)</sup>
15 to 20	–	no	300	150	100	250	1.5	1.5	97004 <sup>(1)</sup>
15 to 20	–	0.5	300	150	100	250	1.5	2.0	97003 <sup>(1)</sup>
20	20	0.5	300	120	70	250	1.4	1.5	97018 <sup>(1)</sup>
35	+15/–20	1	425	110	70	175	1.0	0.7	97009 <sup>(1)</sup>
50	20	1	425	90	60	150	0.8	0.7	97019
<b>General industrial types</b>									
3.3	25	–	24	400	–	650	6.0	8.0	97013 <sup>(1)</sup>
9.4	25	–	60	150	100	300	1.8	3.0	97011 <sup>(1)</sup>

#### Note

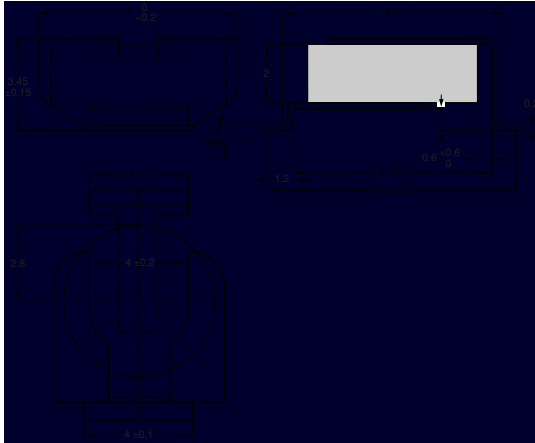
1. These types pass ITU-K20-21-45 edition 2003 telecommunication protection recommendation.



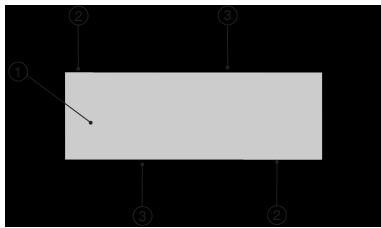
**PTC OUTLINES**

**DIMENSIONS OF SOLDER LANDS** in millimeters

PTC SMD ceramic size: 6.5 mm.



**DIMENSIONS** in millimeters



MATERIAL INFORMATION		
REF.	DESCRIPTION	MATERIAL AND REMARKS
1	ceramic	BaTiO <sub>3</sub> doped
2	metallization	NiCr Ag layer (vacuum deposition)
3	leadframe	Ni plated phosphor bronze material covered by PbSn8 solder layer

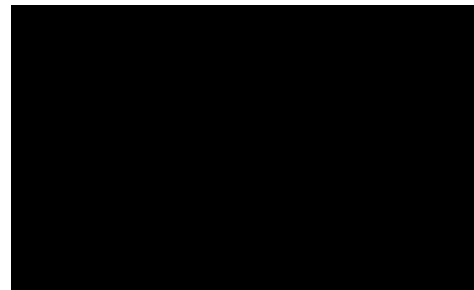
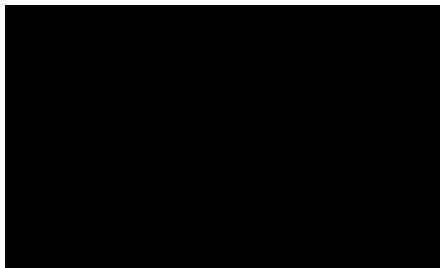
**SOLDERING CONDITIONS**

This SMD thermistor is only suitable for reflow soldering, in accordance with “CECC 00802”. Soldering processes which can be used are reflow (infrared and convection heating) and vapour phase. The maximum temperature of 260 °C during 10 s should not be exceeded and no liquid flux should be allowed to reach the ceramic body.

Typical examples of a soldering processes that will provide reliable joints without damage, are shown below.

Reflow soldering.

Vapour phase soldering.



Typical values (solid line).  
Process limits (dotted lines).

Typical values (solid line).  
Process limits (dotted lines).

**HANDLING PRECAUTIONS**

The special leadframe construction and the applied processes do not allow high handling forces on the component. Because of the nature of PTC ceramic material the component should not be touched with bare hands, as the residue of perspiration can influence component behaviour at high temperatures.

Handling forces vertically applied to the centre of the component should be limited to 5 N in the non-soldered condition and to 10 N in the soldered. These forces should not be exceeded during the handling, transportation and packaging of the soldered product.

For those applications where higher handling forces can be present, a re-inforced version is available on request.